

Amendments to the Specification:

Please replace paragraph [0033] with the following rewritten paragraph:

In accordance with an embodiment of the present invention for accomplishing the second object, there is provided a semiconductor package, comprising: a semiconductor chip within an opening of a circuit board on the upper and lower surfaces of which two circuit patterns are respectively formed, the lower surface of the semiconductor chip and the ~~lower surface of the circuit pattern formed the~~ lower surface of the circuit board being on a same plane; electric connection means respectively connecting the input/output pads of the semiconductor chips to the circuit pattern formed on the upper surface of the circuit board; a plurality of conductive via holes electrically connecting the circuit patterns formed on the upper and lower surfaces of the circuit board to each other; a plurality of ball lands on which a plurality of conductive balls are fusion-bonded, the ball lands being formed on the circuit patterns formed on the upper and lower surfaces of the circuit board; and an encapsulation for protecting the semiconductor chip and the connection means from the external environment.